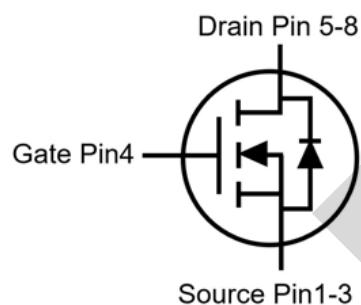
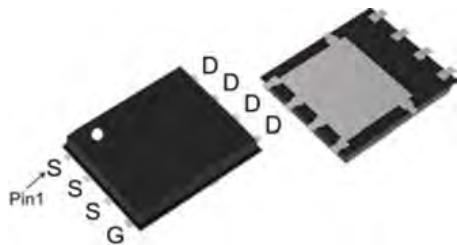


Trench N-channel Power MOSFET

MSR8R5N04D33

PDFN3*3



V_{DS}	40	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	7.0	$\text{m}\Omega$
I_D	49	A

Features

- 1、Low on – resistance
- 2、Package PDFN3*3
- 3、TrenchFET Power MOSFET
- 4、Halogen free

Applications

- 1、Load Switch for Portable Devices
- 2、DC/DC Converter

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V(BR)DSS$	Drain-Source breakdown voltage		40	V
V_{GS}	Gate-Source voltage		± 20	V
I_S	Diode continuous forward current	$T_C=25^\circ\text{C}$	49	A
I_D	Continuous drain current @ $V_{GS}=10\text{V}$	$T_C=25^\circ\text{C}$	49	A
		$T_C=100^\circ\text{C}$	39.2	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	160	A
EAS	Avalanche energy, single pulsed ②		72.6	mJ
P_D	Maximum power dissipation	$T_C=25^\circ\text{C}$	37.8	W
$T_{STG,TJ}$	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	3.3	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	60	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DSS(on)}	Drain-Source On-State Resistance ④	V _{GS} =10V, I _D =15A	--	7.0	8.5	mΩ
		V _{GS} =4.5V, I _D =8A	--	9.7	13	mΩ

Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1MHz	--	1320	--	pF
C _{oss}	Output Capacitance		--	141	--	pF
C _{rss}	Reverse Transfer Capacitance		--	103	--	pF
Q _g (10V)	Total Gate Charge	V _{DS} =20V, I _D =10A , V _{GS} =10V	--	13.7	--	nC
Q _{gs}	Gate-Source Charge		--	1.1	--	nC
Q _{gd}	Gate-Drain Charge		--	4.8	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DS} =20V, V _{GS} =10V, R _L =3.3Ω, I _D =1A	--	8.1	--	ns
Tr	Turn-on Rise Time		--	15	--	ns
Td(off)	Turn-Off Delay Time		--	32	--	ns
Tf	Turn-Off Fall Time		--	12	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

V _{SD}	Forward on voltage	I _{SD} =15A,V _{GS} =0V	--	0.81	1.2	V
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Notes:

- ① Pulse width limited by maximum allowable junction temperature
- ② Limited by TJmax, starting TJ = 25°C, L = 0.3mH, RG = 25Ω, IAS = 22A, VGS = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle≤ 2%

Typical Characteristics

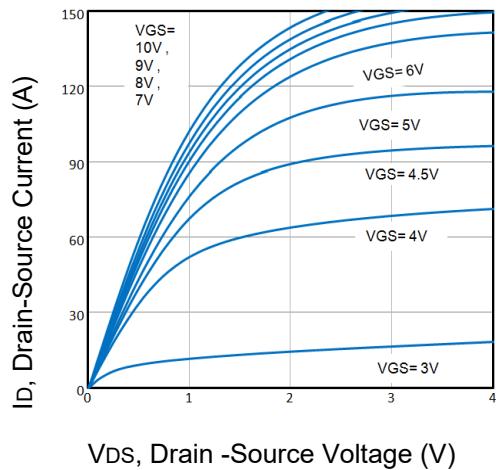


Fig1. Typical Output Characteristics

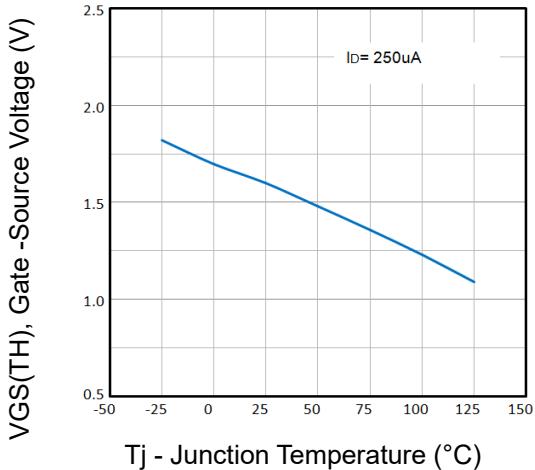


Fig2. $V_{GS(TH)}$ Voltage Vs. Temperature

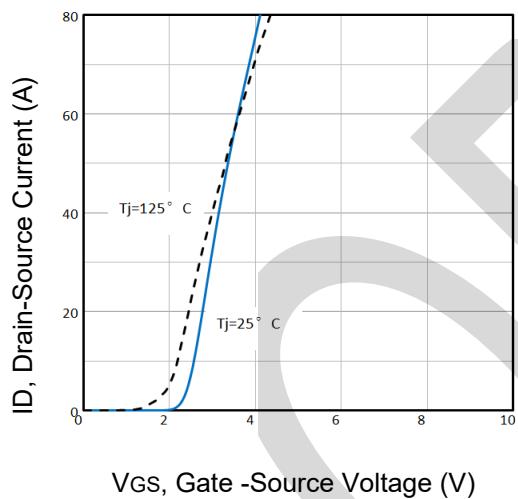


Fig3. Typical Transfer Characteristics

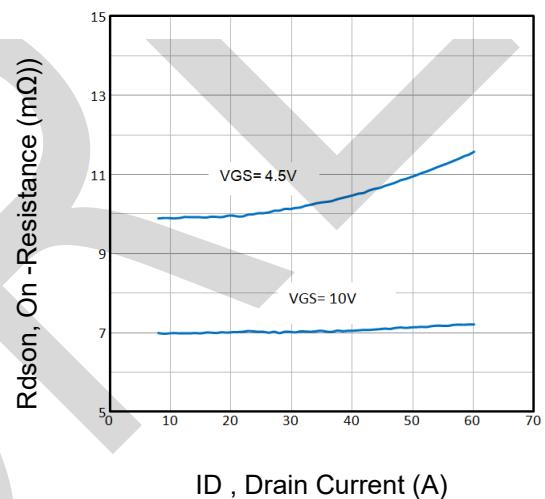


Fig4. On-Resistance vs. Drain Current and Gate Voltage

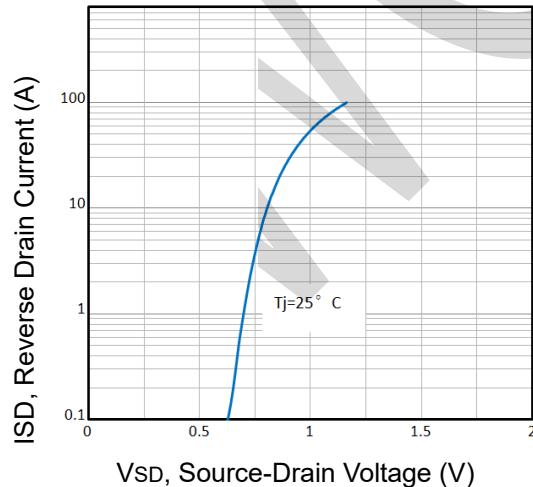


Fig5. Typical Source-Drain Diode Forward Voltage

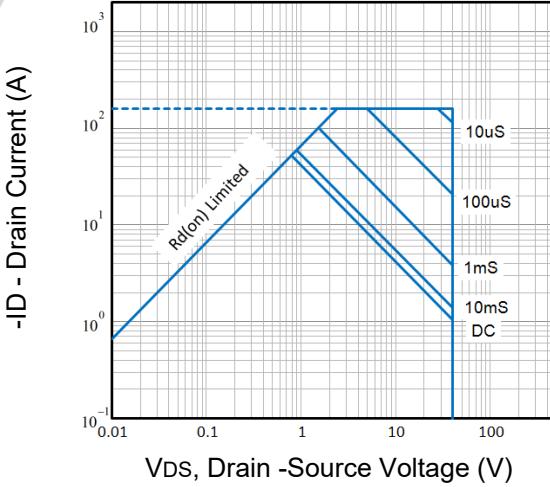


Fig6. Maximum Safe Operating Area

Typical Characteristics

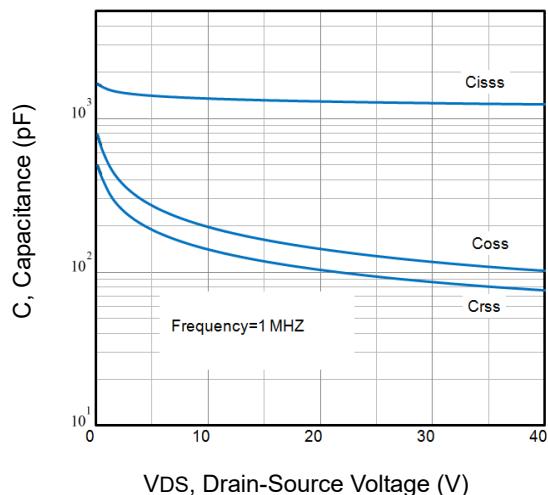


Fig7. Typical Capacitance Vs. Drain-Source Voltage

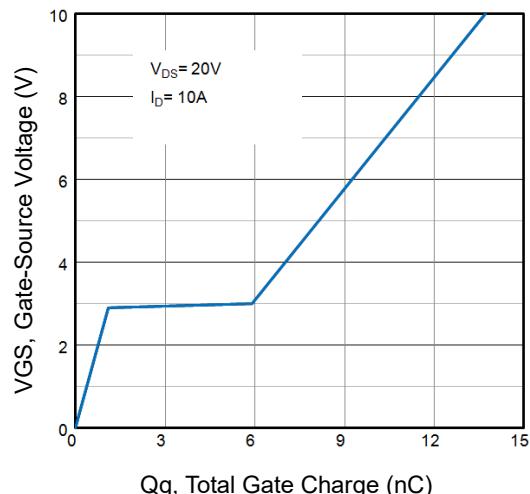


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

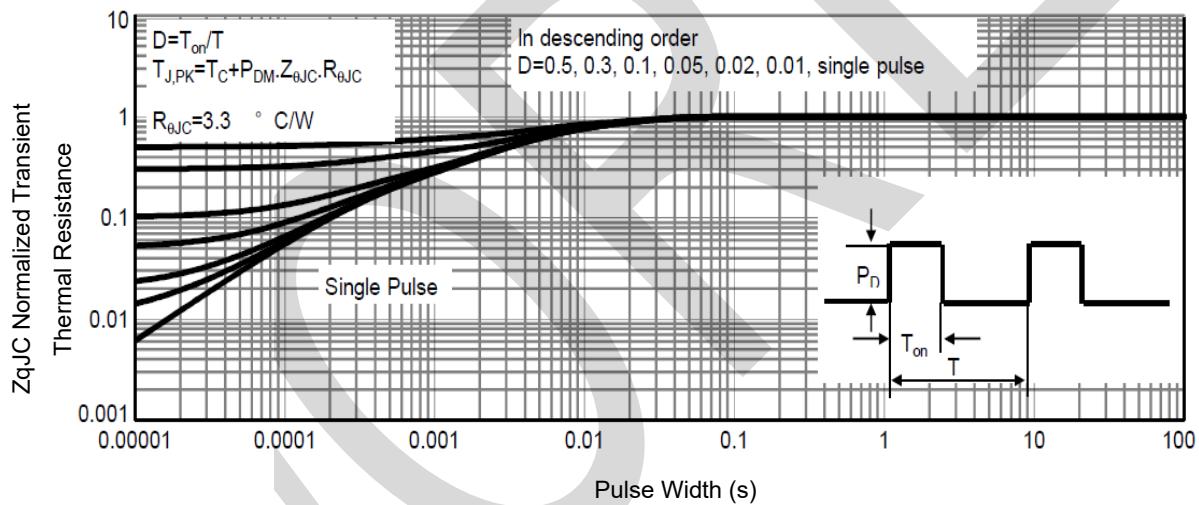
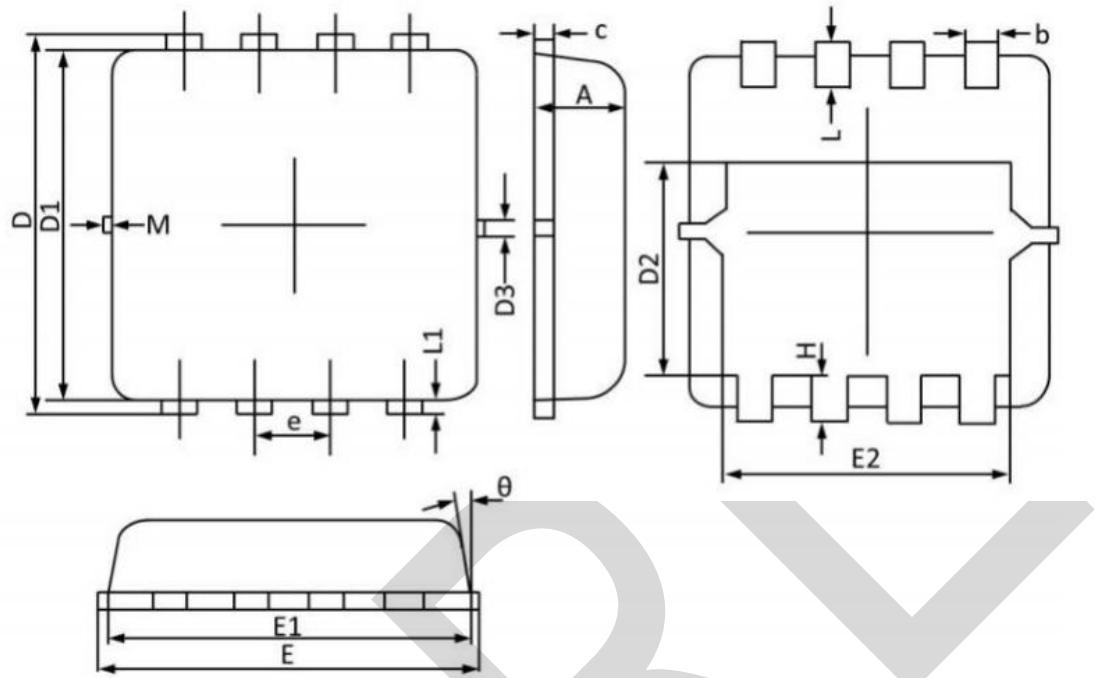


Fig9. Normalized Maximum Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS



unit : mm

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15